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## **Link-Asia International MedTech Group Limited**

**環亞國際醫療科技集團有限公司**

*(incorporated in the Cayman Islands with limited liability)*

**(Stock code: 1143)**

### **LAPSE OF PLACING AGREEMENT**

Reference is made to the announcements of Link-Asia International MedTech Group Limited (the “**Company**”) dated 19 June 2023, 10 July 2023 and 31 July 2023 (the “**Announcements**”) in relation to the Placing Agreement entered into between the Company and the Placing Agent in respect of the Placing. Unless otherwise specified, capitalised terms used in this announcement shall have the same meanings as set out in the Announcements.

Due to the recent market conditions, the Board announces that as the conditions set out in the Placing Agreement were not fully fulfilled by 21 August 2023, the Placing Agreement lapsed and the Placing will not proceed. All rights, obligations and liabilities of the parties thereunder in relation to the Placing shall cease and the Placing Agent shall be released from all obligations pursuant to the Placing Agreement, and none of the parties shall have any claim against each other under the Placing Agreement, save for any rights or obligations which may accrue prior to the date of such termination.

The Board is of the view that the lapse of the Placing Agreement has no material adverse impact on the operation and financial position of the Company as a whole.

By Order of the Board

**Link-Asia International MedTech Group Limited**

**Lin Dailian**

*Chairman and executive Director*

Hong Kong, 21 August 2023

*As at the date of this announcement, the Board comprises Mr. Lin Dailian (Chairman), Mr. Liu Zhiwei, Ms. Lin Xiaoshan and Ms. Bian Sulan as executive Directors; Mr. Li Huiwu and Mr. Chak Chi Shing as independent non-executive Directors.*